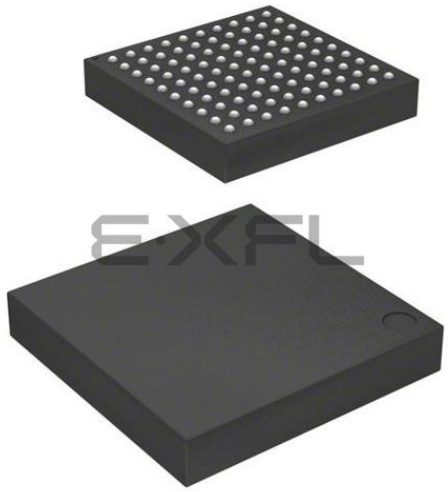
Renesas Electronics America Inc - R5F52315ADLA#20 Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	RXv2
Core Size	32-Bit Single-Core
Speed	54MHz
Connectivity	CANbus, EBI/EMI, I²C, IrDA, SCI, SD/SDIO, SPI, SSI, USB OTG
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	79
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 24x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TFLGA
Supplier Device Package	100-TFLGA (5.5x5.5)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f52315adla-20

1. Overview

1.1 Outline of Specifications

Table 1.1 lists the specifications, and Table 1.2 gives a comparison of the functions of the products in different packages.
Table 1.1 is for products with the greatest number of functions, so the number of peripheral modules and channels will differ in accordance with the package type. For details, see Table 1.2, Comparison of Functions for Different Packages.

Table 1.1 Outline of Specifications (1/4)

Classification	Module/Function	Description
CPU	CPU	• Maximum operating frequency: 54 MHz • 32-bit RX CPU (RX v2) • Minimum instruction execution time: One instruction per clock cycle • Address space: 4-Gbyte linear • Register set General purpose: Sixteen 32-bit registers Control: Ten 32-bit registers Accumulator: Two 72-bit registers • Basic instructions: 75 (variable-length instruction format) • Floating-point instructions: 11 • DSP instructions: 23 • Addressing modes: 10 • Data arrangement Instructions: Little endian Data: Selectable as little endian or big endian • On-chip 32-bit multiplier: 32-bit × 32-bit → 64-bit • On-chip divider: 32-bit ÷ 32-bit → 32 bits • Barrel shifter: 32 bits • Memory protection unit (MPU)
	FPU	• Single precision (32-bit) floating point • Data types and floating-point exceptions in conformance with the IEEE754 standard
Memory	ROM	• Capacity: 128/256/384/512 Kbytes • Up to 32 MHz: No-wait memory access 32 to 54 MHz: Wait state required. No wait state if the instruction is served by a ROM accelerator hit. • Programming/erasing method: Serial programming (asynchronous serial communication/USB communication), self-programming
	RAM	• Capacity: 32/64 Kbytes • 54 MHz, no-wait memory access
	E2 DataFlash	• Capacity: 8 Kbytes • Number of erase/write cycles: 1,000,000 (typ)
MCU operating mode		Single-chip mode, on-chip ROM enabled expansion mode, and on-chip ROM disabled expansion mode (software switching)
Clock	Clock generation circuit	• Main clock oscillator, sub-clock oscillator, low-speed on-chip oscillator, high-speed on-chip oscillator, PLL frequency synthesizer, USB-dedicated PLL frequency synthesizer, and IWDT-dedicated on-chip oscillator • Oscillation stop detection: Available • Clock frequency accuracy measurement circuit (CAC) • Independent settings for the system clock (ICLK), peripheral module clock (PCLK), external bus clock (BCLK), and FlashIF clock (FCLK) The CPU and system sections such as other bus masters run in synchronization with the system clock (ICLK): 54 MHz (at max.) MTU2a runs in synchronization with the PCLKA: 54 MHz (at max.) The ADCLK for the S12AD runs in synchronization with the PCLKD: 54 MHz (at max.) Peripheral modules other than MTU2a and S12ADE run in synchronization with the PCLKB: 32 MHz (at max.) Devices connected to external buses run in synchronization with the BCLK: 32 MHz (at max.) The flash peripheral circuit runs in synchronization with the FCLK: 32 MHz (at max.)
Resets		RES# pin reset, power-on reset, voltage monitoring reset, watchdog timer reset, independent watchdog timer reset, and software reset
Voltage detection	Voltage detection circuit (LVDAb)	• When the voltage on VCC falls below the voltage detection level, an internal reset or internal interrupt is generated. Voltage detection circuit 0 is capable of selecting the detection voltage from 4 levels Voltage detection circuit 1 is capable of selecting the detection voltage from 14 levels Voltage detection circuit 2 is capable of selecting the detection voltage from 4 levels

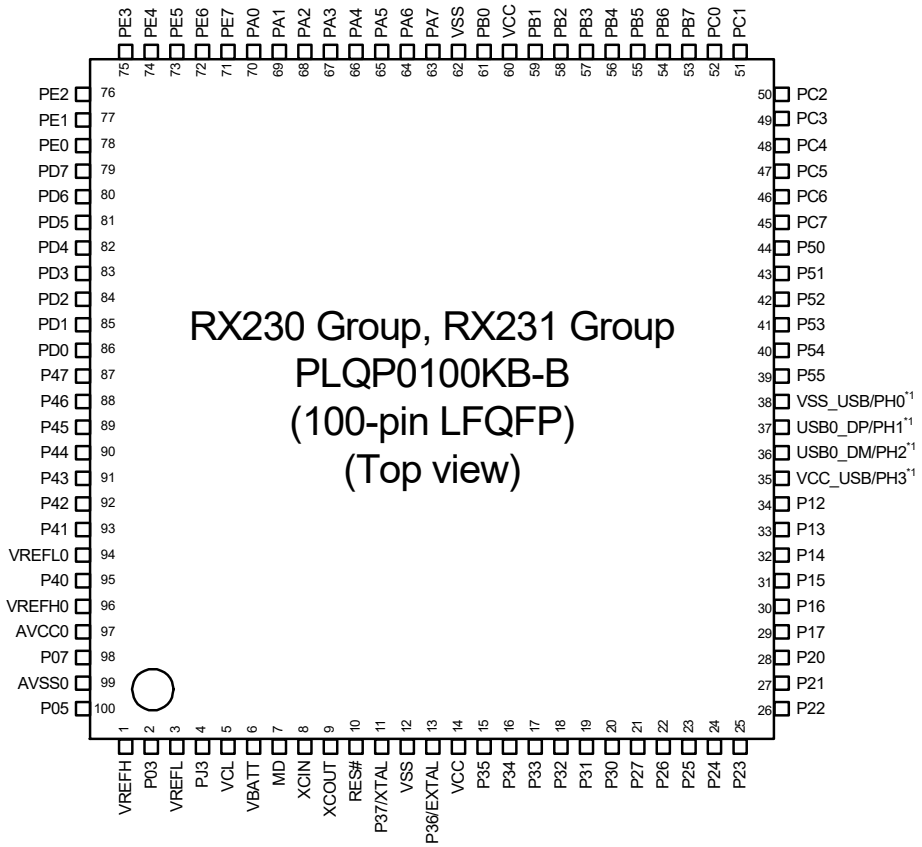
Table 1.1 Outline of Specifications (4/4)

Classification	Module/Function	Description
Communication functions	Serial Sound Interface (SSI)	• 1 channel • Capable of duplex communications • Various serial audio formats supported • Master/slave function supported • Programmable word clock or bit clock generation function • 8/16/18/20/22/24/32-bit data formats supported • On-chip 8-stage FIFO for transmission/reception • Supports WS continue mode in which the SSIWS signal is not stopped.
	SD Host Interface (SDHIa)	• 1 channel • Transfer speed : Default speed mode (8MB/s) • SD memory card interface (1 bit / 4bits SD bus) • MMC, eMMC Backward-compatible are supported. • SD Specifications Part 1: Compliant with Physical Layer Specification Ver.3.01 (Not support DDR) Part E1: SDIO Specification Ver. 3.00 • Error check function: CRC7 (command), CRC16 (data) • Interrupt Source: Card access interrupt, SDIO access interrupt, Card detection interrupt, SD buffer access interrupt • DMA transfer sources: SD_BUF write, SD_BUF read • Card detection, Write protection
Encryption functions	Trusted Secure IP (TSIP-Lite)	• Access management circuit • Encryption engine 128- or 256-bit key sizes of AES Block cipher mode of operation: GCM, ECB, CBC, CMAC, XTS, CTR, GCTR • Hash function • True random number generator • Prevention from illicit copying of a key
12-bit A/D converter (S12ADE)		• 12 bits (24 channels × 1 unit) • 12-bit resolution • Minimum conversion time: 0.83 µs per channel when the ADCLK is operating at 54 MHz • Operating modes Scan mode (single scan mode, continuous scan mode, and group scan mode) Group A priority control (only for group scan mode) • Sampling variable Sampling time can be set up for each channel. • Self-diagnostic function • Double trigger mode (A/D conversion data duplicated) • Detection of analog input disconnection • A/D conversion start conditions A software trigger, a trigger from a timer (MTU, TPU), an external trigger signal, or ELC • Event linking by the ELC
Temperature sensor (TEMPSA)		• 1 channel • The voltage output from the temperature sensor is converted into a digital value by the 12-bit A/D converter.
12-bit D/A converter (R12DAA)		• 2 channels • 12-bit resolution • Output voltage: 0.4 to AVCC0-0.5V
CRC calculator (CRC)		• CRC code generation for arbitrary amounts of data in 8-bit units • Select any of three generating polynomials: $X^8 + X^2 + X + 1$, $X^{16} + X^{15} + X^2 + 1$, or $X^{16} + X^{12} + X^5 + 1$ • Generation of CRC codes for use with LSB-first or MSB-first communications is selectable.
Comparator B (CMPBa)		• 2 channels × 2 units • Function to compare the reference voltage and the analog input voltage • Window comparator operation or standard comparator operation is selectable
Capacitive touch sensing unit (CTSU)		Detection pin: 24 channels
Data operation circuit (DOC)		Comparison, addition, and subtraction of 16-bit data
Power supply voltages/Operating frequencies		VCC = 1.8 to 2.4 V: 8 MHz, VCC = 2.4 to 2.7 V: 16 MHz, VCC = 2.7 to 5.5 V: 54 MHz
Operating temperature range		D version: –40 to +85°C, G version: –40 to +105°C
Packages		100-pin TFLGA (PTLG0100KA-A) 5.5 × 5.5 mm, 0.5 mm pitch 100-pin LFQFP (PLQP0100KB-B) 14 × 14 mm, 0.5 mm pitch 64-pin WFLGA (PWLG0064KA-A) 5 × 5 mm, 0.5 mm pitch 64-pin HWQFN (PWQN0064KC-A) 9 × 9 mm, 0.5 mm pitch 64-pin LFQFP (PLQP0064KB-C) 10 × 10 mm, 0.5 mm pitch 48-pin HWQFN (PWQN0048KB-A) 7 × 7 mm, 0.5 mm pitch 48-pin LFQFP (PLQP0048KB-B) 7 × 7 mm, 0.5 mm pitch
Debugging interfaces		FINE interface

Table 1.2 Comparison of Functions for Different Packages

Module/Functions		RX230 Group			RX231 Group		
		100 Pins	64 Pins	48 Pins	100 Pins	64 Pins	48 Pins
External bus	External bus	16 bit	Not supported		16 bit	Not supported	
Interrupts	External interrupts	NMI, IRQ0 to IRQ7	NMI, IRQ0, IRQ1, IRQ4 to IRQ7	NMI, IRQ0, IRQ1, IRQ4 to IRQ7	NMI, IRQ0 to IRQ7	NMI, IRQ0, IRQ1, IRQ4 to IRQ7	NMI, IRQ0, IRQ1, IRQ4 to IRQ7
DMA	DMA controller	4 channels (DMAC0 to DMAC3)			4 channels (DMAC0 to DMAC3)		
	Data transfer controller	Available			Available		
Timers	16-bit timer pulse unit	6 channels (TPU0 to TPU5)			6 channels (TPU0 to TPU5)		
	Multi-function timer pulse unit 2	6 channels (MTU0 to MTU5)			6 channels (MTU0 to MTU5)		
	Port output enable 2	POE0# to POE3#, POE8#			POE0# to POE3#, POE8#		
	8-bit timer	2 channels× 2 units			2 channels× 2 units		
	Compare match timer	2 channels× 2 units			2 channels× 2 units		
	Low power timer	1 channel			1 channel		
	Realtime clock	Available		Not supported	Available		Not supported
	Watchdog timer	Available			Available		
	Independent watchdog timer	Available			Available		
Communication functions	Serial communications interfaces (SCIg)	6 channels (SCI0, 1, 5, 6, 8, 9)	5 channels (SCI1, 5, 6, 8, 9)	4 channels (SCI1, 5, 6, 8)	6 channels (SCI0, 1, 5, 6, 8, 9)	5 channels (SCI1, 5, 6, 8, 9)	4 channels (SCI1, 5, 6, 8)
	IrDA interface	1 channel (SCI5)			1 channel (SCI5)		
	Serial communications interfaces (SCIh)	1 channel (SCI12)			1 channel (SCI12)		
	I²C bus interface	1 channel			1 channel		
	CAN module	Not supported			1 channel*1		
	Serial peripheral interface	1 channel			1 channel		
	USB 2.0 host/function module	Not supported			1 channel		
	Serial sound interface	1 channel			1 channel		
	SD Host Interface	Not supported			1 channel*1		Not supported
Capacitive touch sensing unit		24 channels	10 channels	6 channels	24 channels	10 channels	6 channels
12-bit A/D converter (including high-precision channels)		24 channels (8 channels)	12 channels (6 channels)	8 channels (4 channels)	24 channels (8 channels)	12 channels (6 channels)	8 channels (4 channels)
Temperature sensor		Available			Available		
D/A converter		2 channels		Not supported	2 channels		Not supported
CRC calculator		Available			Available		
Event link controller		Available			Available		
Comparator B		4 channels			4 channels		
Packages		100-pin TFLGA 100-pin LFQFP	64-pin WFLGA 64-pin HWQFN 64-pin LFQFP	48-pin HWQFN 48-pin LFQFP	100-pin TFLGA 100-pin LFQFP	64-pin WFLGA 64-pin HWQFN 64-pin LFQFP	48-pin HWQFN 48-pin LFQFP

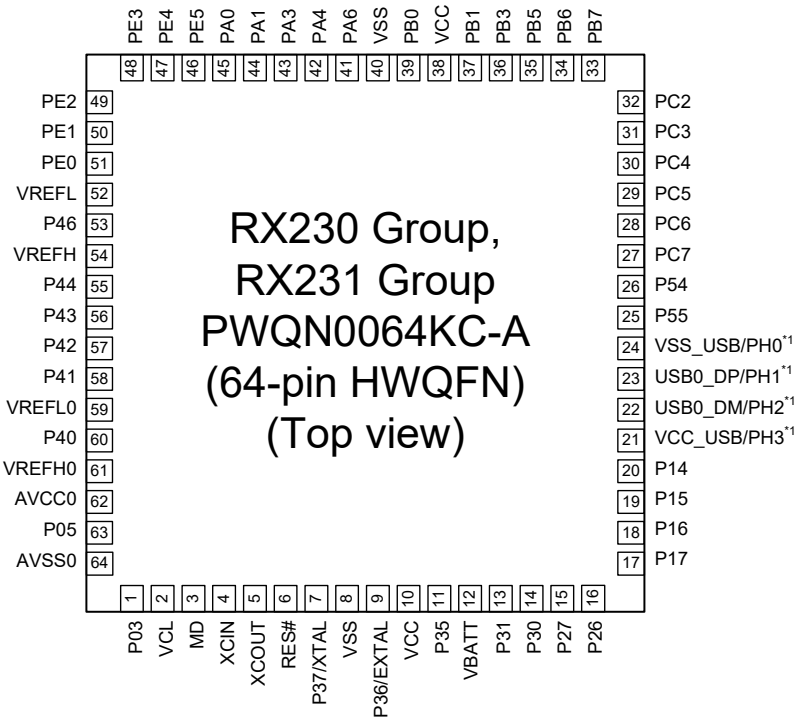
Note 1. Only for chip version B



Note: This figure indicates the power supply pins and I/O port pins.
For the pin configuration, see the table “List of Pins and Pin Functions (100-Pin LFQFP)”.

Note 1. RX230: PH0, PH1, PH2, PH3
RX231: VSS_USB, USB0_DP, USB0_DM, VCC_USB

Figure 1.4 Pin Assignments of the 100-Pin LFQFP



Note: This figure indicates the power supply pins and I/O port pins.
For the pin configuration, see the table “List of Pins and Pin Functions (64-Pin LFQFP/HWQFN)”.
Note: It is recommended to connect an exposed die pad to VSS.

Note 1. RX230: PH0, PH1, PH2, PH3
RX231: VSS_USB, USB0_DP, USB0_DM, VCC_USB

Figure 1.6 Pin Assignments of the 64-Pin HWQFN

(9) Floating-point status word (FPSW)

The floating-point status word (FPSW) indicates the results of floating-point operations.
When an exception handling enable bit (Ej) enables the exception handling (Ej = 1), the exception cause can be identified by checking the corresponding Cj flag in the exception handling routine. If the exception handling is masked (Ej = 0), the occurrence of exception can be checked by reading the Fj flag at the end of a series of processing. Once the Fj flag has been set to 1, this value is retained until it is cleared to 0 by software (j = X, U, Z, O, or V).

2.3 Accumulator

The accumulator (ACC0 or ACC1) is a 72-bit register used for DSP instructions. The accumulator is handled as a 96-bit register for reading and writing. At this time, when bits 95 to 72 of the accumulator are read, the value where the value of bit 71 is sign extended is read. Writing to bits 95 to 72 of the accumulator is ignored. ACC0 is also used for the multiply and multiply-and-accumulate instructions; EMUL, EMULU, FMUL, MUL, and RMPA, in which case the prior value in ACC0 is modified by execution of the instruction.
Use the MVTACGU, MVTACHI, and MVTACLO instructions for writing to the accumulator. The MVTACGU, MVTACHI, and MVTACLO instructions write data to bits 95 to 64, the higher-order 32 bits (bits 63 to 32), and the lower-order 32 bits (bits 31 to 0), respectively.
Use the MVFACGU, MVFACHI, MVFACMI, and MVFACLO instructions for reading data from the accumulator. The MVFACGU, MVFACHI, MVFACMI, and MVFACLO instructions read data from the guard bits (bits 95 to 64), higher-order 32 bits (bits 63 to 32), the middle 32 bits (bits 47 to 16), and the lower-order 32 bits (bits 31 to 0), respectively.

Table 4.1 List of I/O Registers (Address Order) (17/33)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK ≥ PCLK	ICLK <PCLK
0008 C0A4h	PORTJ	Open Drain Control Register 0	ODR0	8	8, 16	2 or 3 PCLKB	2 ICLK
0008 C0C0h	PORT0	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0C1h	PORT1	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0C2h	PORT2	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0C3h	PORT3	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0C4h	PORT4	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0C5h	PORT5	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0CAh	PORTA	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0CBh	PORTB	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0CCh	PORTC	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0CDh	PORTD	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0CEh	PORTE	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0D1h	PORTH	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0D2h	PORTJ	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0E1h	PORT1	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0E2h	PORT2	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0E3h	PORT3	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0E5h	PORT5	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0EAh	PORTA	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0EBh	PORTB	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0ECh	PORTC	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0EDh	PORTD	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0EEh	PORTE	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0F1h	PORTH	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0F2h	PORTJ	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C100h	MPC	CS Output Enable Register	PFCSE	8	8	2 or 3 PCLKB	2 ICLK
0008 C104h	MPC	Address Output Enable Register 0	PFAOE0	8	8, 16	2 or 3 PCLKB	2 ICLK
0008 C105h	MPC	Address Output Enable Register 1	PFAOE1	8	8, 16	2 or 3 PCLKB	2 ICLK
0008 C106h	MPC	External Bus Control Register 0	PFBCR0	8	8, 16	2 or 3 PCLKB	2 ICLK
0008 C107h	MPC	External Bus Control Register 1	PFBCR1	8	8, 16	2 or 3 PCLKB	2 ICLK
0008 C11Fh	MPC	Write-Protect Register	PWPR	8	8	2 or 3 PCLKB	2 ICLK
0008 C120h	PORT	Port Switching Register B	PSRB	8	8	2 or 3 PCLKB	2 ICLK
0008 C121h	PORT	Port Switching Register A	PSRA	8	8	2 or 3 PCLKB	2 ICLK
0008 C143h	MPC	P03 Pin Function Control Register	P03PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C145h	MPC	P05 Pin Function Control Register	P05PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C147h	MPC	P07 Pin Function Control Register	P07PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C14Ah	MPC	P12 Pin Function Control Register	P12PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C14Bh	MPC	P13 Pin Function Control Register	P13PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C14Ch	MPC	P14 Pin Function Control Register	P14PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C14Dh	MPC	P15 Pin Function Control Register	P15PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C14Eh	MPC	P16 Pin Function Control Register	P16PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C14Fh	MPC	P17 Pin Function Control Register	P17PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C150h	MPC	P20 Pin Function Control Register	P20PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C151h	MPC	P21 Pin Function Control Register	P21PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C152h	MPC	P22 Pin Function Control Register	P22PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C153h	MPC	P23 Pin Function Control Register	P23PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C154h	MPC	P24 Pin Function Control Register	P24PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C155h	MPC	P25 Pin Function Control Register	P25PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C156h	MPC	P26 Pin Function Control Register	P26PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C157h	MPC	P27 Pin Function Control Register	P27PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C158h	MPC	P30 Pin Function Control Register	P30PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C159h	MPC	P31 Pin Function Control Register	P31PFS	8	8	2 or 3 PCLKB	2 ICLK

Table 4.1 List of I/O Registers (Address Order) (19/33)

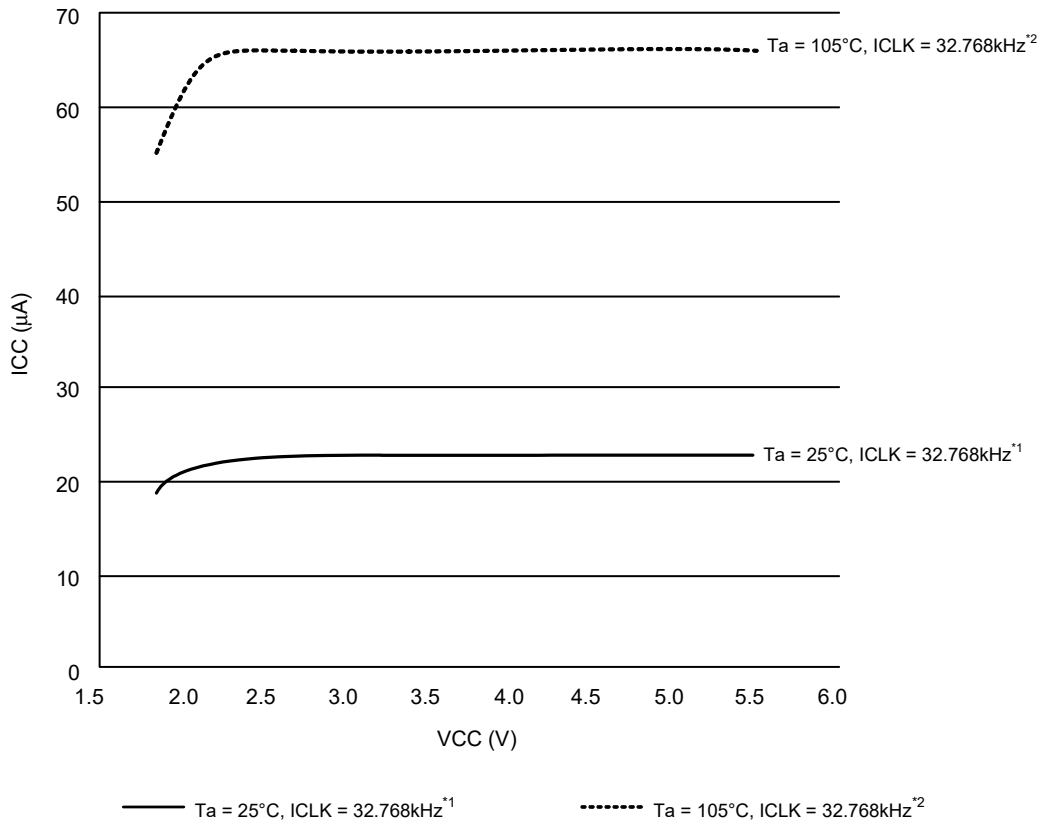
Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK ≥ PCLK	ICLK <PCLK
0008 C1B3h	MPC	PE3 Pin Function Control Register	PE3PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C1B4h	MPC	PE4 Pin Function Control Register	PE4PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C1B5h	MPC	PE5 Pin Function Control Register	PE5PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C1B6h	MPC	PE6 Pin Function Control Register	PE6PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C1B7h	MPC	PE7 Pin Function Control Register	PE7PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C1C8h	MPC	PH0 Pin Function Control Register	PH0PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C1C9h	MPC	PH1 Pin Function Control Register	PH1PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C1CAh	MPC	PH2 Pin Function Control Register	PH2PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C1CBh	MPC	PH3 Pin Function Control Register	PH3PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C1D3h	MPC	PJ3 Pin Function Control Register	PJ3PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C290h	SYSTEM	Reset Status Register 0	RSTSR0	8	8	4 or 5 PCLKB	2 or 3 ICLK
0008 C291h	SYSTEM	Reset Status Register 1	RSTSR1	8	8	4 or 5 PCLKB	2 or 3 ICLK
0008 C293h	SYSTEM	Main Clock Oscillator Forced Oscillation Control Register	MOFCR	8	8	4 or 5 PCLKB	2 or 3 ICLK
0008 C297h	SYSTEM	Voltage Monitoring Circuit Control Register	LVCMPCR	8	8	4 or 5 PCLKB	2 or 3 ICLK
0008 C298h	SYSTEM	Voltage Detection Level Select Register	LVDLVLR	8	8	4 or 5 PCLKB	2 or 3 ICLK
0008 C29Ah	SYSTEM	Voltage Monitoring 1 Circuit Control Register 0	LVD1CR0	8	8	4 or 5 PCLKB	2 or 3 ICLK
0008 C29Bh	SYSTEM	Voltage Monitoring 2 Circuit Control Register 0	LVD2CR0	8	8	4 or 5 PCLKB	2 or 3 ICLK
0008 C29Dh	SYSTEM	VBATT Control Register	VBATTCR	8	8	4 or 5 PCLKB	2 or 3 ICLK
0008 C29Eh	SYSTEM	VBATT Status Register	VBATTSR	8	8	4 or 5 PCLKB	2 or 3 ICLK
0008 C29Fh	SYSTEM	VBATT Pin Voltage Drop Detection Interrupt Control Register	VBTLVDICR	8	8	4 or 5 PCLKB	2 or 3 ICLK
0008 C400h	RTC	64-Hz Counter	R64CNT	8	8	2 or 3 PCLKB	2 ICLK
0008 C402h	RTC	Second Counter	RSECCNT	8	8	2 or 3 PCLKB	2 ICLK
0008 C402h	RTC	Binary Counter 0	BCNT0	8	8	2 or 3 PCLKB	2 ICLK
0008 C404h	RTC	Minute Counter	RMINCNT	8	8	2 or 3 PCLKB	2 ICLK
0008 C404h	RTC	Binary Counter 1	BCNT1	8	8	2 or 3 PCLKB	2 ICLK
0008 C406h	RTC	Hour Counter	RHRCNT	8	8	2 or 3 PCLKB	2 ICLK
0008 C406h	RTC	Binary Counter 2	BCNT2	8	8	2 or 3 PCLKB	2 ICLK
0008 C408h	RTC	Day-of-Week Counter	RWKCNT	8	8	2 or 3 PCLKB	2 ICLK
0008 C408h	RTC	Binary Counter 3	BCNT3	8	8	2 or 3 PCLKB	2 ICLK
0008 C40Ah	RTC	Date Counter	RDAYCNT	8	8	2 or 3 PCLKB	2 ICLK
0008 C40Ch	RTC	Month Counter	RMONCNT	8	8	2 or 3 PCLKB	2 ICLK
0008 C40Eh	RTC	Year Counter	RYRCNT	16	16	2 or 3 PCLKB	2 ICLK
0008 C410h	RTC	Second Alarm Register	RSECAR	8	8	2 or 3 PCLKB	2 ICLK
0008 C410h	RTC	Binary Counter 0 Alarm Register	BCNT0AR	8	8	2 or 3 PCLKB	2 ICLK
0008 C412h	RTC	Minute Alarm Register	RMINAR	8	8	2 or 3 PCLKB	2 ICLK
0008 C412h	RTC	Binary Counter 1 Alarm Register	BCNT1AR	8	8	2 or 3 PCLKB	2 ICLK
0008 C414h	RTC	Hour Alarm Register	RHRAR	8	8	2 or 3 PCLKB	2 ICLK
0008 C414h	RTC	Binary Counter 2 Alarm Register	BCNT2AR	8	8	2 or 3 PCLKB	2 ICLK
0008 C416h	RTC	Day-of-Week Alarm Register	RWKAR	8	8	2 or 3 PCLKB	2 ICLK
0008 C416h	RTC	Binary Counter 3 Alarm Register	BCNT3AR	8	8	2 or 3 PCLKB	2 ICLK
0008 C418h	RTC	Date Alarm Register	RDAYAR	8	8	2 or 3 PCLKB	2 ICLK
0008 C418h	RTC	Binary Counter 0 Alarm Enable Register	BCNT0AER	8	8	2 or 3 PCLKB	2 ICLK
0008 C41Ah	RTC	Month Alarm Register	RMONAR	8	8	2 or 3 PCLKB	2 ICLK
0008 C41Ah	RTC	Binary Counter 1 Alarm Enable Register	BCNT1AER	8	8	2 or 3 PCLKB	2 ICLK
0008 C41Ch	RTC	Year Alarm Register	RYRAR	16	16	2 or 3 PCLKB	2 ICLK
0008 C41Ch	RTC	Binary Counter 2 Alarm Enable Register	BCNT2AER	16	16	2 or 3 PCLKB	2 ICLK
0008 C41Eh	RTC	Year Alarm Enable Register	RYRAREN	8	8	2 or 3 PCLKB	2 ICLK
0008 C41Eh	RTC	Binary Counter 3 Alarm Enable Register	BCNT3AER	8	8	2 or 3 PCLKB	2 ICLK
0008 C422h	RTC	RTC Control Register 1	RCR1	8	8	2 or 3 PCLKB	2 ICLK
0008 C424h	RTC	RTC Control Register 2	RCR2	8	8	2 or 3 PCLKB	2 ICLK
0008 C426h	RTC	RTC Control Register 3	RCR3	8	8	2 or 3 PCLKB	2 ICLK

5.2 DC Characteristics

Table 5.3 DC Characteristics (1)

Conditions: 2.7 V ≤ VCC = VCC_USB ≤ 5.5 V, 2.7 V ≤ AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item			Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Schmitt trigger input voltage	RIIC input pin (except for SMBus, 5 V tolerant)		V_{IH}	VCC × 0.7	—	5.8	V	
	Ports 12, 13, 16, 17, port B5 (5 V tolerant)			VCC × 0.8	—	5.8		
	Ports 14 to 15, ports 20 to 27, ports 33 to 37, ports 50 to 55, ports A0 to A7, ports B0 to B4, B6, B7 ports C0 to C7, ports D0 to D7, ports E0 to E7, port J3, Ports 30 to 32 (when time capture event input is not selected), RES#			VCC × 0.8	—	VCC + 0.3		
	Ports 03, 05, 07, ports 40 to 47			AVCC0 × 0.8	—	AVCC0 + 0.3		
	Ports 30 to 32 (when time capture event input is selected)	When VCC is supplied		VCC × 0.8	—	VCC + 0.3		
		When VBATT is supplied		VBATT × 0.8	—	VBATT + 0.3		
	Ports 03, 05, 07, ports 40 to 47		V_{IL}	–0.3	—	AVCC0 × 0.2		
	RIIC input pin (except for SMBus)			–0.3	—	VCC × 0.3		
	Other than RIIC input pin or ports 30 to 32			–0.3	—	VCC × 0.2		
	Ports 30 to 32 (when time capture event input is selected)	When VCC is supplied		–0.3	—	VCC × 0.3		
		When VBATT is supplied		–0.3	—	VBATT × 0.3		
	Ports 03, 05, 07, ports 40 to 47		ΔV_T	AVCC0 × 0.1	—	—		
	RIIC input pin (except for SMBus)			VCC × 0.05	—	—		
	Ports 12, 13, 16, 17, Port B5			VCC × 0.05	—	—		
	Other than RIIC input pin			VCC × 0.1	—	—		
Input level voltage (except for Schmitt trigger input pins)	MD		V_{IH}	VCC × 0.9	—	VCC + 0.3	V	
	EXTAL (external clock input)			VCC × 0.8	—	VCC + 0.3		
	RIIC input pin (SMBus)			2.1	—	VCC + 0.3		
	MD		V_{IL}	–0.3	—	VCC × 0.1		
	EXTAL (external clock input)			–0.3	—	VCC × 0.2		
	RIIC input pin (SMBus)			–0.3	—	0.8		



Note 1. All peripheral operations except any BGO operation are operating normally. Indicates the average of the typical samples through actual measurement during product evaluation.
Note 2. All peripheral operations except any BGO operation are operating at maximum. Indicates the average of the upper-limit samples through actual measurement during product evaluation.

Figure 5.3 Voltage Dependency in Low-Speed Operating Mode (Reference Data)

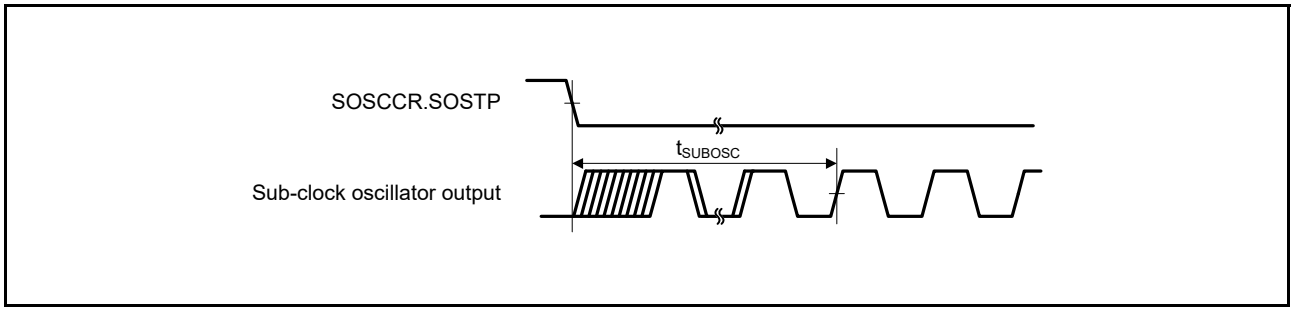


Figure 5.30 Sub-Clock Oscillation Start Timing

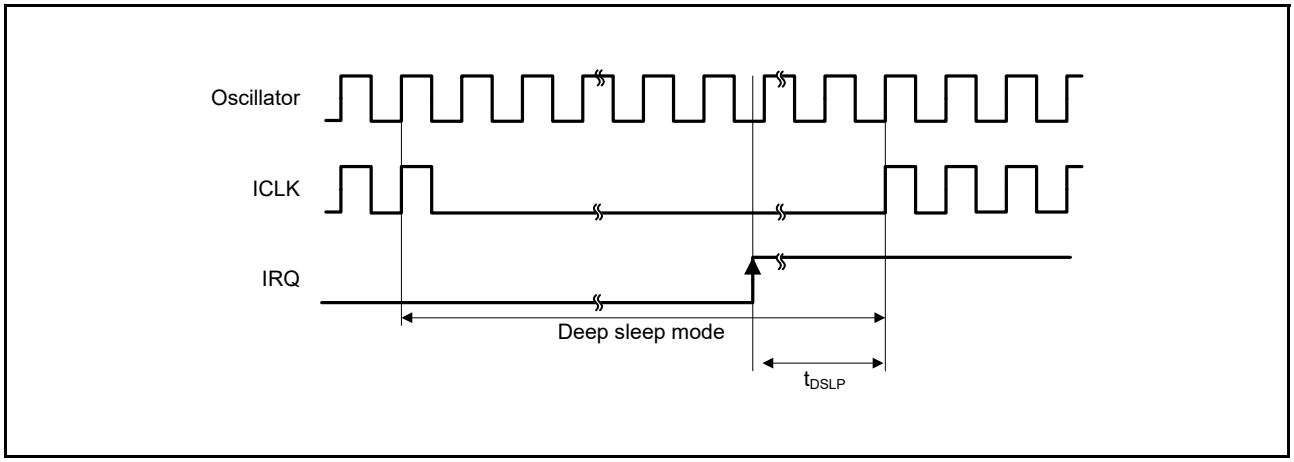


Figure 5.35 Deep Sleep Mode Recovery Timing

Table 5.32 Operating Mode Transition Time

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Mode before Transition	Mode after Transition	ICLK Frequency	Transition Time			Unit
			Min.	Typ.	Max.	
High-speed operating mode	Middle-speed operating modes	8 MHz	—	10	—	µs
Middle-speed operating modes	High-speed operating mode	8 MHz	—	37.5	—	µs
Low-speed operating mode	Middle-speed operating mode, high-speed operating mode	32.768 kHz	—	215	—	µs
Middle-speed operating mode, high-speed operating mode	Low-speed operating mode	32.768 kHz	—	185	—	µs

Note: Values when the frequencies of PCLKA, PCLKB, PCLKD, FCLK, and BCLK are not divided.

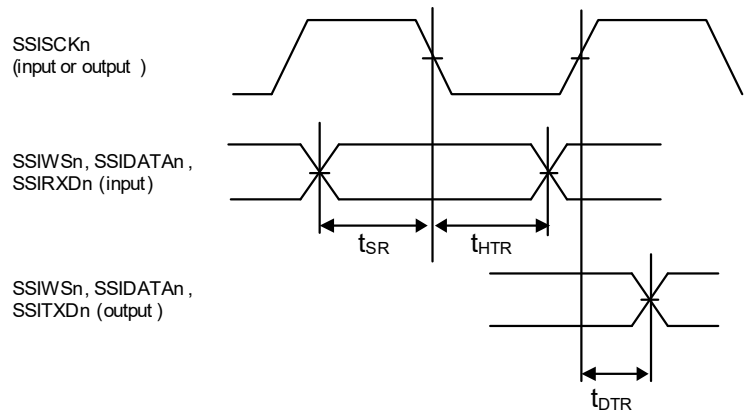
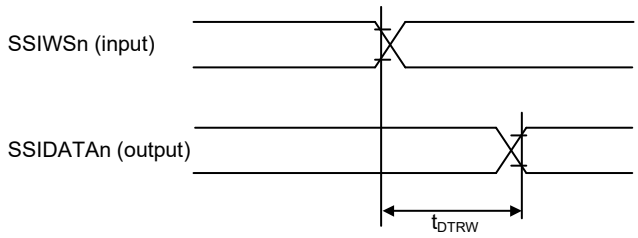


Figure 5.62 SSI Transmission/Reception Timing (SSICR.SCKP=1)



Note. Timing to output the MSB bit during slave transmission from SSIWSn
when DEL = 1 and SDTA = 0 or DEL = 1, SDTA = 1, and SWL[2:0] = DWL[2:0]

Figure 5.63 SSIDATA Output Delay After SSIWSn Changing Edge

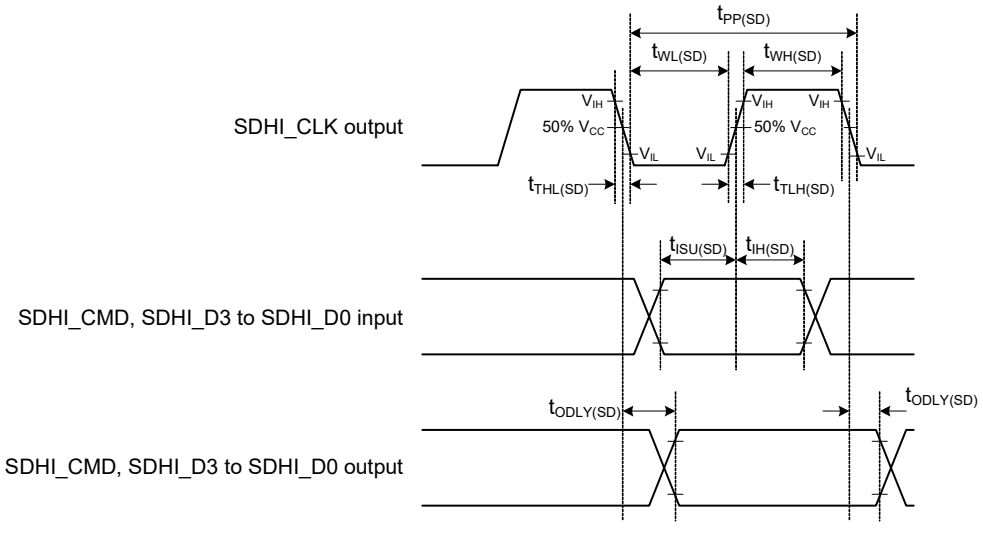


Figure 5.64 SD Host Interface Input/Output Signal Timing

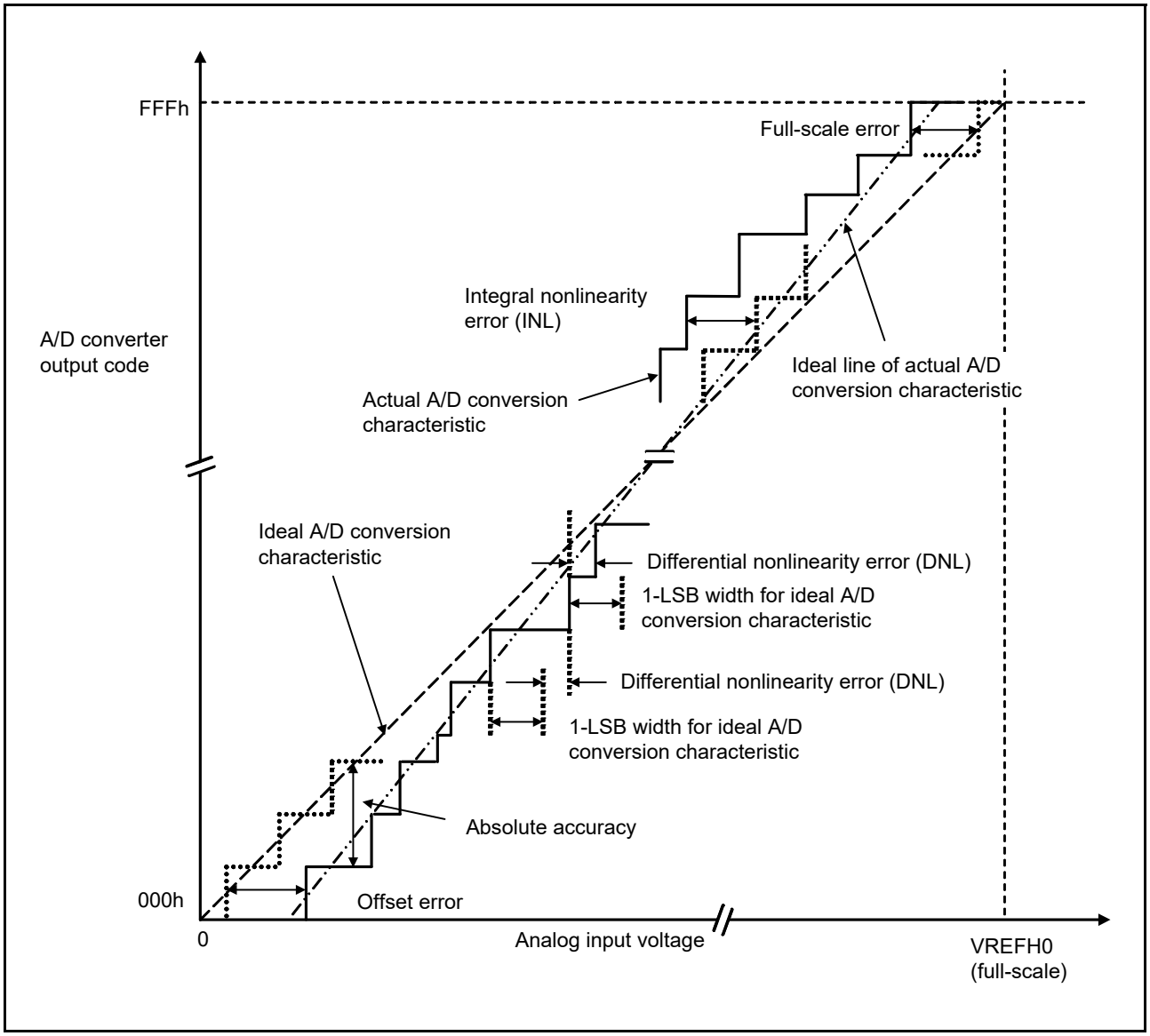


Figure 5.69 Illustration of A/D Converter Characteristic Terms

Absolute accuracy

Absolute accuracy is the difference between output code based on the theoretical A/D conversion characteristics and the actual A/D conversion result. When measuring absolute accuracy, the voltage at the midpoint of the width of analog input voltage (1-LSB width), that can meet the expectation of outputting an equal code based on the theoretical A/D conversion characteristics, is used as an analog input voltage. For example, if 12-bit resolution is used and if reference voltage (VREFH0 = 3.072 V), then 1-LSB width becomes 0.75 mV, and 0 mV, 0.75 mV, 1.5 mV, ... are used as analog input voltages.

If analog input voltage is 6 mV, absolute accuracy = ±5 LSB means that the actual A/D conversion result is in the range of 003h to 00Dh, although an output code, 008h, can be expected from the theoretical A/D conversion characteristics.

Integral non-linearity error (INL)

The integral non-linearity error is the maximum deviation between the ideal line when the measured offset and full-scale errors are zeroed, and the actual output code.

Table 5.59 Characteristics of Power-On Reset Circuit and Voltage Detection Circuit (2)

Conditions: 1.8 V ≤ VCC0 = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Wait time after power-on reset cancellation	At normal startup*1	t_{POR}	—	9.1	—	ms	Figure 5.74
	During fast startup time*2	t_{POR}	—	1.6	—		
Wait time after voltage monitoring 0 reset cancellation	Power-on voltage monitoring 0 reset disabled*1	t_{LVD0}	—	568	—	µs	Figure 5.75
	Power-on voltage monitoring 0 reset enabled*2		—	100	—		
Wait time after voltage monitoring 1 reset cancellation		t_{LVD1}	—	100	—	µs	Figure 5.76
Wait time after voltage monitoring 2 reset cancellation		t_{LVD2}	—	100	—	µs	Figure 5.77
Response delay time		t_{det}	—	—	350	µs	Figure 5.73
Minimum VCC down time*3		t_{VOFF}	350	—	—	µs	Figure 5.73, VCC = 1.0 V or above
Power-on reset enable time		$t_{W(POR)}$	1	—	—	ms	Figure 5.74, VCC = below 1.0 V
LVD operation stabilization time (after LVD is enabled)		$Td_{(E-A)}$	—	—	300	µs	Figure 5.76, Figure 5.77
Hysteresis width (power-on rest (POR))		V_{PORH}	—	110	—	mV	
Hysteresis width (voltage detection circuit: LVD1 and LVD2)		V_{LVH}	—	70	—	mV	When Vdet1_0 to Vdet1_4 is selected
			—	60	—		When Vdet1_5 to Vdet1_9 is selected
			—	50	—		When Vdet1_A or Vdet1_B is selected
			—	40	—		When Vdet1_C or Vdet1_D is selected
			—	60	—		When LVD2 is selected

Note: These characteristics apply when noise is not superimposed on the power supply. When a setting is made so that the voltage detection level overlaps with that of the voltage detection circuit (LVD1), it cannot be specified which of LVD1 and LVD2 is used for voltage detection.

Note 1. When OFS1.(LVDAS, FASTSTUP) = 11b.

Note 2. When OFS1.(LVDAS, FASTSTUP) ≠ 11b.

Note 3. The minimum VCC down time indicates the time when VCC is below the minimum value of voltage detection levels V_{POR}, V_{det0}, V_{det1}, and V_{det2} for the POR/LVD.

5.11 Oscillation Stop Detection Timing

Table 5.60 Oscillation Stop Detection Timing

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Detection time	t_{dr}	—	—	1	ms	Figure 5.78

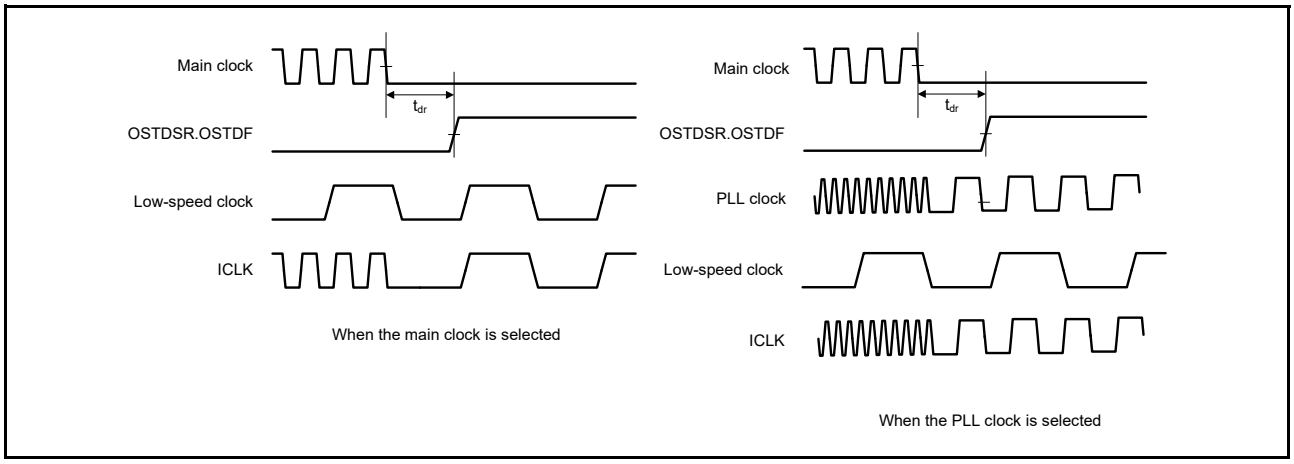


Figure 5.78 Oscillation Stop Detection Timing

Table 5.64 ROM (Flash Memory for Code Storage) Characteristics (3) Middle-Speed Operating Mode

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V

Temperature range for the programming/erasure operation: T_a = –40 to +85°C

Item		Symbol	FCLK = 1 MHz			FCLK = 8 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	8-byte	t_{P8}	—	152	1367	—	97.9	936	µs
Erasure time	2-Kbyte	t_{E2K}	—	8.8	279.7	—	5.9	221	ms
	512-Kbyte (when block erase command is used)	t_{E512K}	—	928	19221	—	191	4108	ms
	512-Kbyte (when all-block erase command is used)	t_{EA512K}	—	923	19015	—	185	3901	ms
Blank check time	8-byte	t_{BC8}	—	—	85.0	—	—	50.88	µs
	2-Kbyte	t_{BC2K}	—	—	1870	—	—	402	µs
Erase operation forced stop time		t_{SED}	—	—	28.0	—	—	21.3	µs
Start-up area switching setting time		t_{SAS}	—	13.0	573.3	—	7.7	451	ms
Access window time		t_{AWS}	—	13.0	573.3	—	7.7	451	ms
ROM mode transition wait time 1		t_{DIS}	2.0	—	—	2.0	—	—	µs
ROM mode transition wait time 2		t_{MS}	3.0	—	—	3.0	—	—	µs

Note: The time until each operation of the flash memory is started after instructions are executed by software is not included.

Note: The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.

Note: The frequency accuracy of FCLK must be within ±3.5%.

5.15 Usage Notes

5.15.1 Connecting VCL Capacitor and Bypass Capacitors

This MCU integrates an internal voltage-down circuit, which is used for lowering the power supply voltage in the internal MCU automatically to the optimum level. A 4.7-µF capacitor needs to be connected between this internal voltage-down power supply (VCL pin) and the VSS pin. Figure 5.80 to Figure 5.82 shows how to connect external capacitors. Place an external capacitor close to the pins. Do not apply the power supply voltage to the VCL pin.
Insert a multilayer ceramic capacitor as a bypass capacitor between each pair of the power supply pins. Implement a bypass capacitor as closer to the MCU power supply pins as possible. Use a recommended value of 0.1 µF as the capacitance of the capacitors. For the capacitors related to crystal oscillation, see section 9, Clock Generation Circuit in the User's Manual: Hardware. For the capacitors related to analog modules, also see section 43, 12-Bit A/D Converter (S12ADE) in the User's Manual: Hardware.
For notes on designing the printed circuit board, see the descriptions of the application note, the Hardware Design Guide (R01AN1411EJ). The latest version can be downloaded from the Renesas Electronics website.

Rev.	Date	Description		Classification
		Page	Summary	
1.10	Oct 30, 2015	142	Table 5.45 A/D Conversion Characteristics (1): Conditions and Voltage Range of Analog Input (Max.), changed	
		143	Table 5.46 A/D Conversion Characteristics (2): Conditions changed	
		144	Table 5.47 A/D Conversion Characteristics (3): Conditions changed	
		145	Table 5.48 A/D Conversion Characteristics (4): Conditions changed	
		146	Table 5.49 A/D Conversion Characteristics (5): Conditions changed and Absolute accuracy (Test Conditions) deleted	
		153	Table 5.57 Characteristics of Power-On Reset Circuit and Voltage Detection Circuit (1), changed	TN-RX*-A137A/E
		154	Table 5.58 Characteristics of Power-On Reset Circuit and Voltage Detection Circuit (2), changed	
		155	Figure 5.73 Power-On Reset Timing and Figure 5.74 Voltage Detection Circuit Timing (Vdet0), changed	
		159	Table 5.62 ROM (Flash Memory for Code Storage) Characteristics (2) High-Speed Operating Mode: Note changed	
		160	Table 5.63 ROM (Flash Memory for Code Storage) Characteristics (3) Middle-Speed Operating Mode: Note changed	
		161	Table 5.65 E2 DataFlash Characteristics (2): high-speed operating mode, Note changed	
		161	Table 5.66 E2 DataFlash Characteristics (3): middle-speed operating mode, Conditions and Note changed	
		163	Figure 5.79 Connecting Capacitors (100 Pins), changed	
		164	Figure 5.80 Connecting Capacitors (64 Pins), changed	
		165	Figure 5.81 Connecting Capacitors (48 Pins), changed	
		Appendix 1. Package Dimensions		
		167	Figure B 100 -Pin LQFP (PLQP0100KB-B), changed	TN-RX*-A137A/E
		170	Figure E 64 -Pin LQFP (PLQP0064KB-C), changed	TN-RX*-A137A/E
		172	Figure G 48 -Pin LQFP (PLQP0048KB-B), changed	TN-RX*-A137A/E
1.20	Sep 28, 2018	Features		
		1	SD host interface (optional: one channel) SD memory/ SDIO 1-bit or 4-bit SD bus supported, Note deleted	TN-RX*-A145A/E
		1. Overview		
		6	Table 1.2 Comparison of Functions for Different Packages, changed (deletion of IRQ2 on 64-pin package)	
		6	Table 1.2 Comparison of Functions for Different Packages, Note 1 added	TN-RX*-A145A/E
		7	Table 1.3 List of Products: D Version (Ta = –40 to +85°C) (1/2), changed	TN-RX*-A145A/E
		9	Table 1.4 List of Products: G Version (Ta = –40 to +105°C) (1/2), changed	TN-RX*-A145A/E
		11	Figure 1.1 How to Read the Product Part Number, changed	TN-RX*-A145A/E
		16	Table 1.5 Pin Functions (4/4), changed (changes in description for VCC_USB)	TN-RX*-A201A/E
		24	Table 1.6 List of Pins and Pin Functions (100-Pin TFLGA) (2/3), changed (UPSEL was added to the column of P35)	
		24	Table 1.6 List of Pins and Pin Functions (100-Pin TFLGA) (2/3), changed (USB0_VBUS was added to the column of PB5)	
		26	Table 1.7 List of Pins and Pin Functions (100-Pin LFQFP) (1/3), changed (UPSEL was added to the column of P35)	
		29	Table 1.8 List of Pins and Pin Functions (64-Pin WFLGA) (1/2), changed (UPSEL was added to the column of P35)	
		30	Table 1.8 List of Pins and Pin Functions (64-Pin WFLGA) (2/2), changed (USB0_VBUS was added to the column of PB5)	
		31	Table 1.9 List of Pins and Pin Functions (64-Pin LFQFP/HWQFN) (1/2), changed (UPSEL was added to the column of P35)	
		31	Table 1.9 List of Pins and Pin Functions (64-Pin LQFP/HWQFN) (1/2), changed (USB0_VBUS was added to the column of PB5)	
		33	Table 1.10 List of Pins and Pin Functions (48-Pin LFQFP/HWQFN) (1/2), changed (UPSEL was added to the column of P35)	
		33	Table 1.10 List of Pins and Pin Functions (48-Pin LFQFP/HWQFN) (1/2), changed	TN-RX*-A145A/E
		5. Electrical Characteristics		
		92	Table 5.18 Output Values of Voltage (1), changed	TN-RX*-A201A/E
		92	Table 5.19 Output Values of Voltage (2), changed	TN-RX*-A201A/E

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

   Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

   ¾ The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   ¾ The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   ¾ The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   ¾ When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

   ¾ The characteristics of Microprocessing unit or Microcontroller unit products in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.